Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.062”**

**.062”**

**ANODE**

**.051 X .051”**

**.009”**

**Top Material: Al**

**Backside Material: Ag**

**Bond Pad Size = .051 x .051”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .062” X .062” DATE: 11/9/21**

**MFG: SILICON SUPPLIES THICKNESS .009” P/N: 1N4981**

**DG 10.1.2**

#### Rev B, 7/1